

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	14833	257,81,82,225,433,434,680,681,660,626,629-652,643,759,792,737,738,730,704,713,749.ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:26
S2	6	S1 and ((IC (integrated adj circuit)) with ((photoelectric near converter) photoreception))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:51
S3	3	("3151278" "4587421").PN	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/26 15:32
S4	2882	S1 and ((IC (integrated adj circuit)) with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:27
S5	216427	S4 an ((wir\$3 redistribution) with (seal\$3 near resin) with (light near cap))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:08
S6	0	S4 and ((wir\$3 redistribution) with (seal\$3 near resin) with (light near cap))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:36
S7	2088	S4 and ((wir\$3 redistribution))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:36
S8	0	"74" and ((seal\$3 near resin) with (light near cap))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:37
S9	0	S7 and ((seal\$3 near resin) with (light near cap))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:34

S10	202	S7 and (seal\$3 near resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:37
S11	2	S10 and (light near (lid cap cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:38
S12	150	S10 and (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 15:38
S13	3	("5956576" "6218730" "6285079").PN	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/26 16:00
S14	353908	S4 an (photoelectric photoreception)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:09
S15	33	S4 and (photoelectric photoreception)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:25
S16	21	S4 and ((seal\$3 near resin) with open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:34
S17	499035	"257"/\$ccls. "438"/\$ccls. "361"/\$ccls	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:17
S18	35791	S17 and ((IC (integrated adj circuit)) with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:18

S19	125	S18 and ((seal\$3 near resin) with open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:24
S20	440	(seal\$3 near resin) with (hole open\$3 groove recess) with (cover lid cap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:25
S21	6	S20 and (photoelectric photoreception)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:25
S22	43	S20 and ((IC (integrated adj circuit)) with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:32
S23	25785	(IC (integrated adj circuit)) with (photoelectric photoreception photodetector sensor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:48
S24	0	S23 and ((seal\$3 near resin) with (light near cap))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:35
S25	41	S23 and ((seal\$3 near resin) with (cap lid cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:52
S26	2741	((seal\$3 near resin) with (cap lid cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:54
S27	440	((seal\$3 near resin) with (open\$3 hole recess groove) with (cap lid cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:48

S28	33	S27 and (photoelectric photoreception photodetector sensor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:48
S29	52964	(IC (integrated adj circuit) chip die) with (photoelectric photodetector sensor photoreception)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:52
S30	8	S29 and ((seal\$3 near resin) with surround)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:53
S31	77	S29 and ((seal\$3 near resin) with (cap lid cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/26 16:54
S32	6	("20020109137" "20020117694" "5862248" "6088471" "6330145" "6512381").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/26 17:05